

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

24.04.2026

WÜRTH
ELEKTRONIK
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-009my 330x490mm	50201012	9	VS	1	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		2	
		35	L2	3	A01
C-RS-FR4-ML-0.508mm-035+035-TG150-HF-...	50203006	508			
		35	L3		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	124		4	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		5	B00
		35	L4		
C-RS-FR4-ML-0.508mm-035+035-TG150-HF-...	50203006	508		6	A02
		35	L5		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	62		7	
A-RS Kupferfolie-009my 330x490mm	50201012	9	RS	8	

Thickness after Pressing

B00:

1440 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1595 µm

Dmin:

1285 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

1550 µm

Tol+:

155 µm

Tol-:

155 µm

Dmax:

1705 µm

Dmin:

1395 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

1422 µm

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